

ABSTRACT

An object is to provide a copper paste for joining that is unlikely to generate voids in a sintering process of a coating film formed thereof to achieve a sufficiently high joining rate to a target member to be joined. A copper paste for joining contains: two or more copper powders having different particle sizes; and a solvent; wherein one of the copper powders has an increase rate of a crystallite size, $(D2-D1)/D1 \times 100$, of 5% or more, where D1 (nm) represents a crystallite size at 150°C and D2 (nm) represents a crystallite size at 250°C; the solvent has a boiling point of 150°C or higher and lower than 300°C; and the proportion of the total amount of the copper powders is 88 mass% or more in 100 mass% of the copper paste.